SPECIFICATIONS

Customer	
Product Name	Multi-layer Chip Varistor
Sunlord Part Number	SDV1005 Series
Customer Part Number	

$[\square New Released, \square Revised]$

SPEC No.: SDV170000

F	Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
	01	/	New release	/	Hai Guo

[This SPEC is total 10 pages including specifications and appendix.] [ROHS Compliant Parts]

Approved By	Checked By	Issued By

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[For Customer approval Only]			Date:	
Qualification Status:	🗌 Full 🗌	Res	stricted 🗌 Rejec	cted
Approved By	Verified By		Re-checked By	Checked By
Comments:				

Caution

All products listed in this specification are developed, designed and intended for use in general electronics equipment. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require especially high reliability, or whose failure, malfunction or trouble might directly cause damage to society, person, or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below. Please contact us for more details if you intend to use our products in the following applications.

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. nuclear control equipment
- 5. military equipment
- 6. Power plant equipment
- 7. Medical equipment
- 8. Transportation equipment (automobiles, trains, ships, etc.)
- 9. Traffic signal equipment
- 10. Disaster prevention / crime prevention equipment
- 11. Data-processing equipment
- 12. Applications of similar complexity or with reliability requirements comparable to the applications listed in the above

1. Scope

This specification applies to SDV1005 Series of multi-layer chip varistors.

Product Description and Identification (Part Number) 2.

- Description 1)
 - SDV1005 Series of multi-layer chip varistors.
- 2) Product Identification (Part Number)

1 Туре SDV Chip Varistor

② External Dimensions (L×W) (mm)		
1005 [0402]	1.0×0.5	

④ Maxin	Maximum Continuous		
Working Voltage			
Example	Nominal Value		
5R5	5.5V		
180	18V		

⑤ Capacitance @1MHz		
Example	Nominal Value	
C050	5pF	
C500	50pF	
C151	150pF	

8	Packinę	9
	Т	Tape & Reel

\bigcirc		Ter	minal Code
	Ρ		Ni, Sn plating

9	Products specifications		
	S	Sb Free	

③ Feature Code		
А	For general use	
E	For ESD	
Н	For high speed	
S	For special request	

(6) Tolerance of Capacitance		
Ν	±30%	
Y	+100%/-50%	
G	Maximum	

(10)	HSF Products
	Hazardous Substance
	Free Products

3. **Electrical Characteristics**

Please refer to Appendix A (Page 8~9).

- 1) Operating and storage temperature range (individual chip without packing): -55° ~ $+125^{\circ}$.
- Storage temperature range (packaging conditions): -10℃~+40℃ RH 70% (Max.). 2)

Shape and Dimensions 4.

Туре

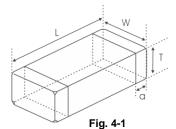
1005

[0402]

Dimensions and recommended PCB pattern for reflow soldering: See Fig.4-1, Fig.4-2 and Table 4-1. 1)

[0.020±0.006]

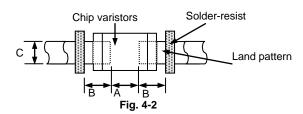
2) Structure: See Fig. 4-3 and Fig. 4-4.



W

0.5±0.15

[0.020±0.006]



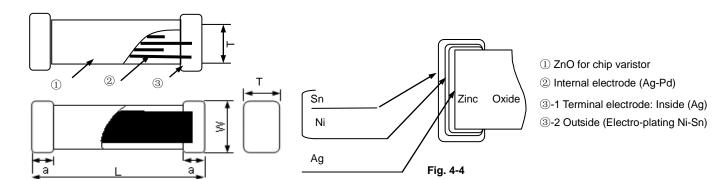


Unit: mm [inch] т А В С а 0.5±0.15 0.25±0.1

0.45~0.55

0.40~0.50

0.45~0.55



[0.010±0.004]

L

1.0±0.15

[0.039±0.006]

5. Test and Measurement Procedures

5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15℃.
- b. Relative Humidity: 65±20%.
- c. Air Pressure: 86kPa to 106kPa.
- 5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:
 - a. Ambient Temperature: 20±2°C
 - b. Relative Humidity: 65±5%.
 - c. Air Pressure: 86kPa to 106kPa.

5.2 Visual Examination

a. Inspection Equipment: $20 \times$ magnifier.

5.3 Electrical Test

Items	Requirements	Test Methods and Remarks				
5.3.1 Varistor Voltage at 1mA DC (V _B)	Refer to Appendix A	Measuring current: 1mA DC Duration: 0.2 to 2 sec				
5.3.2 Capacitance (C)	Refer to Appendix A	Measure source: 0.5 V _{RMS} Test frequency: 1MHz.				
5.3.3 Leakage Current (I _L)	Refer to Appendix A	Measuring voltage: Maximum DC working voltage				
5.3.4 Clamping Voltage (V_c)	Refer to Appendix A	Measuring source: 8/20us waveform, ESD waveform				

5.4 Reliability Test

Items	Requirements	Test Methods and Remarks
5.4.1. Terminal	No removal or split of the termination or other defects shall occur.	 Solder the chip to the testing jig (glass epoxy board shown in Fig.5.4.1-1) using eutectic solder. Then apply a force in the
Strength	Chip F	 direction of the arrow. 2 5N force for SDV1005 series, 3 Keep time: 10±1s.
	Mounting Pad Glass Epoxy Board Fig.5.4.1-1	

Specifications for Multi-layer Chip Varistor

	Specifications for						
5.4.2 Resistance	No visible mechanical damage.	① Solder the chip to the test jig (glass epoxy board shown in					
to Flexure	Type a b c	Fig.5.4.2-1) using a eutectic solder. Then apply a force in the					
		direction shown in Fig.5.4.2-2 . ② Flexure: 2mm.					
	1005[0402] 0.4 1.5 0.5	 Pressurizing Speed: 0.5mm/sec. 					
		 4 Keep time: 30 sec. 					
	Unit: mm [inch]						
		20					
		Flexure					
	Fig.5.4.2-1	Fig.5.4.2-2					
5.4.3	No visible mechanical damage.	 Solder the chip to the testing jig (glass epoxy board shown in 					
Vibration		Fig.5.4.3-1) using eutectic solder.					
	Cu pad Solder mask	② The chip shall be subjected to a simple harmonic motion having					
		total amplitude of 1.5mm, the frequency being varied uniformly					
		between the approximate limits of 10 and 55 Hz.					
		③ The frequency range from 10 to 55 Hz and return to 10 Hz shall					
		be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular					
	Glass Epoxy Board	directions (total of 6 hours).					
	Fig. 5.4.3-1						
5.4.4	① No visible mechanical damage.	① Solder temperature: 240±2℃					
Solderability	② Wetting shall exceed 90% coverage.	② Duration: 3 sec.					
		③ Solder: Sn/3.0Ag/0.5Cu.					
5 4 5 D 1 4		Flux: 25% Resin and 75% ethanol in weight.					
5.4.5 Resistance to Soldering	 No visible mechanical damage. Varistor voltage change: within ±10%. 	① Solder temperature: 260±3℃					
Heat		 ② Duration: 5 sec. ③ The chip shall be stabilized at normal condition for 1~2hours 					
liout		before measuring.					
		④ Solder: Sn/3.0Ag/0.5Cu.					
		5 Flux: 25% Resin and 75% ethanol in weight.					
5.4.6	① No visible mechanical damage.	1 Temperature, Time: -55° C for 30 ± 3 min \rightarrow 125°C for 30 ± 3 min.					
Thermal Shock	② Varistor voltage change: within ±10%.	 Transforming interval: 20sec. (max.) Trated early 120 and 120 					
		 ③ Tested cycle: 100 cycles. ④ The chip shall be stabilized at normal condition for 1~2 hours 					
		before measuring.					
	30 min. 30 min.	before medouring.					
	Ambient						
	Temperature 20 min						
	-55℃ 50 mm. 1						
	Fig 5.4.6-1 ^{20sec.} (max.)						
5.4.7 Resistance	No visible mechanical damage.	① Temperature: -55±2°C					
to Low	 Varistor voltage change: within ±10%. 	(2) Duration: 1000^{+24} hours.					
Temperature		③ The chip shall be stabilized at normal condition for 1~2 hours					
		before measuring.					
5.4.8 Resistance	No visible mechanical damage. Noristor veltage abanged within ±10%	① Temperature: 125±2℃.					
to High Temperature	2 Varistor voltage change: within ±10%.	 ② Duration: 1000⁺²⁴ hours. ③ The chip shall be stabilized at normal condition for 1~2 hours 					
Temperature		before measuring.					
5.4.9	No visible mechanical damage.	1 Temperature: 60±2°C					
Damp Heat	 Varistor voltage change: within ±10%. 	2 Humidity: 90% to 95% RH.					
(Steady States)		3 Duration: 1000 ⁺²⁴ hours.					
		④ The chip shall be stabilized at normal condition for 1~2 hours					
		before measuring.					

Specifications for Multi-layer Chip Varistor

Sumoru	Specifications for M	ulli-layer chip valision Fage 6 01 10
5.4.10 Loading Under Damp Heat 5.4.11 Loading at High Temperature (Life Test)	 No visible mechanical damage. Varistor voltage change: within ±10%. No visible mechanical damage. Varistor voltage change: within ±10%. 	 Temperature: 60±2°C Humidity: 90% to 95% RH. Duration: 1000⁺²⁴ hours. Applied voltage: DC Working Voltage. The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring. Temperature: 125±2°C Duration: 1000⁺²⁴ hours. Applied voltage: DC Working Voltage. The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring.
5.4.12 Maximum Surge Current	 No visible mechanical damage. Varistor voltage change: within ±10%. IEC61000-4-5 standard 1.2/50us-8/20us voltage-current combination pulse 	 Temperature: 25±5°C Humidity: 30% to 65% RH. Number of hit: each 1 time of +/- polarity. Pulse waveform: 8/20 us. Applied current: maximum surge current (I_P). The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring.
5.4.13 Maximum Surge Energy	 No visible mechanical damage. Varistor voltage change: within ±10%. IEC61000-4-5 standard 10/1000us current pulse 	 Temperature :25±5℃ Humidity: 30% to 65% RH. Number of hit: 1 time. Pulse waveform: 10/1000 us. Applied energy: maximum surge energy (E_T). The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring.
5.4.14 ESD Life	 No visible mechanical damage. Varistor voltage change: within ±10%. IEC61000-4-2 standard ESD gun C=150pF R=330Ω 	 Discharge: Contact discharge. Voltage: 8000V (Level 4). Polarity: +, Number: 10 times within 10 sec. The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring.
5.4.15 ESD Test	 No visible mechanical damage. Varistor voltage change: within ±10%. IEC61000-4-2 standard ESD gun C=150pF R=330Ω 	 Discharge: Air discharge. Voltage: 15000V (Special level). Polarity: +, - Number: 10 times within 10 sec. The chip shall be stabilized at normal condition for 1~2 hours before positive and negative direction measuring.

6. Packaging and Storage

6.1 Packaging

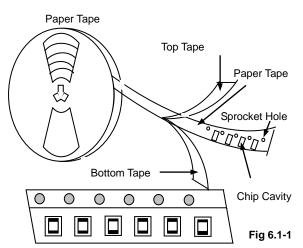
6.1.1 Tape Carrier Packaging:

Packaging code: T

- a. Tape carrier packaging are specified in attached figure Fig.6.1-1~3
- b. Tape carrier packaging quantity please see the following table:

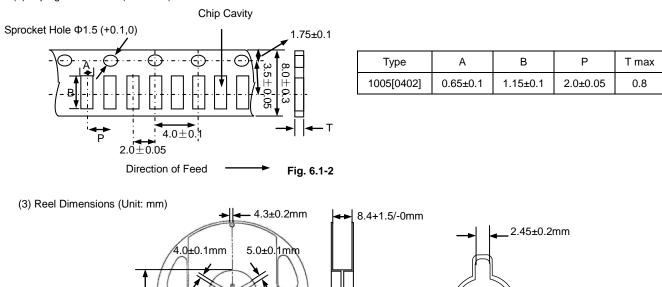
Туре	1005[0402]				
T(mm)	0.5±0.15				
Tape	Paper Tape				
Quantity	10K				

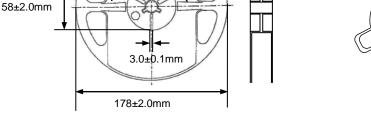
(1) Taping Drawings (Unit: mm)



Remark: The sprocket holes are to the right as the tape is pulled toward the user.

(2) Taping Dimensions (Unit: mm)





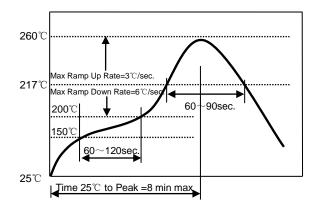
6.2 Storage

- a. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40°C or less and 70% RH or less.
- b. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H₂S).
- c. Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.
- d. Solderability specified in **Clause 5.4.6** shall be guaranteed for 6 months from the date of delivery on condition that they are stored at the environment specified in **Clause 3**. For those parts, which passed more than 6 months shall be checked solder-ability before use.

7. Recommended Soldering Technologies

7.1 Re-flowing Profile:

- \triangle Preheat condition: 150 ~200°C/60~120sec.
- \triangle Allowed time above 217°C: 60~90sec.
- △ Max temp: 260°C
- \triangle Max time at max temp: 10sec.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- \triangle Allowed Reflow time: 2x max.



13.5±0.2mm

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

7.2 Iron Soldering Profile.

- \bigtriangleup $% \label{eq:linear}$ Iron soldering power: Max.30W
- \bigtriangleup $\,$ Pre-heating: 150 $^\circ\!\mathrm{C}$ / 60 sec.
- \bigtriangleup Soldering Tip temperature: 350 $^\circ CMax.$
- \bigtriangleup Soldering time: 3 sec Max.
- \triangle Solder paste: Sn/3.0Ag/0.5Cu
- \bigtriangleup $\,$ Max.1 times for iron soldering

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]

8. Supplier Information

a) Supplier:

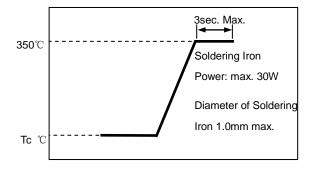
Shenzhen Sunlord Electronics Co., Ltd.

b) Manufacturer:

Shenzhen Sunlord Electronics Co., Ltd.

c) Manufacturing Address:

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China Zip: 518110



Appendix A: Electrical Characteristics (SDV Series of Varistors) I. SDV1005A Series

Part Number	Max. Working Voltage		Varistor Voltage	Max. Clamping Voltage		Rated Single Pulse Transient		Typical Capacitance
Test Condition	<2 DC	0μΑ AC RMS	@1mA DC	8/20µs	ESD	Energy 10/1000µs	Peak Current 8/20µs	@0.5V _{ms} , 1MHz
Units	Volts	Volts	Volts	Volts	Volts	Joules	Amps	pF
Symbol	V_{WDC}	V_{WAC}	V _B	V _C ^{*1}	V _C *2	Eτ	I _P	С
SDV1005A5R5C181 DPTSF	5.5	4.0	10.0-14.0	18	23	0.05	20	180
SDV1005A5R5C231 DPTSF	5.5	4.0	10.0-14.0	18	23	0.05	20	230
SDV1005A5R5C361 DPTSF	5.5	4.0	10.0-14.0	18	23	0.05	20	360
SDV1005A090C121 PTSF	9.0	6.4	11.0-16.0	20	26	0.05	20	120
SDV1005A090C231 PTSF	9.0	6.4	11.0-16.0	20	26	0.05	20	230
SDV1005A140C121 PTSF	14.0	10.0	16.0-22.0	30	39	0.05	20	120

II.SDV1005E Series

Part Number	Max. Working Voltage		Varistor Voltage	Max. Clamping Voltage		Rated Single Pulse Transient		Typical Capacitance
Test Condition	<2 DC	0μΑ AC RMS	@1mA DC	8/20µs	ESD	Energy 10/1000µs	Peak Current 8/20µs	@0.5V _{rms} , 1MHz
Units	Volts	Volts	Volts	Volts	Volts	Joules	Amps	pF
Symbol	V _{WDC}	V _{WAC}	VB	V _C *1	Vc*2	Eτ	I _P	С
SDV1005E5R5C180□PTSF	5.5	4.0	10.0-14.0	18	23	0.005	3	18
SDV1005E5R5C300 DTSF	5.5	4.0	10.0-14.0	18	23	0.005	5	30
SDV1005E5R5C500 DTSF	5.5	4.0	10.0-14.0	18	23	0.01	10	50
SDV1005E5R5C800 DTSF	5.5	4.0	10.0-14.0	18	23	0.02	10	80
SDV1005E5R5C101 DTSF	5.5	4.0	10.0-14.0	18	23	0.05	20	100
SDV1005E090C180 DTSF	9.0	6.4	11.0-16.0	20	26	0.005	3	18
SDV1005E090C300 DTSF	9.0	6.4	11.0-16.0	20	26	0.005	5	30
SDV1005E090C500 DTSF	9.0	6.4	11.0-16.0	20	26	0.01	10	50
SDV1005E090C800 DTSF	9.0	6.4	11.0-16.0	20	26	0.02	15	80
SDV1005E090C101 DTSF	9.0	6.4	11.0-16.0	20	26	0.05	20	100
SDV1005E140C180□PTSF	14.0	10.0	16.0-22.0	30	39	0.005	3	18
SDV1005E140C300 DTSF	14.0	10.0	16.0-22.0	30	39	0.01	5	30
SDV1005E140C500 DTSF	14.0	10.0	16.0-22.0	30	39	0.02	10	50
SDV1005E140C800 DTSF	14.0	10.0	16.0-22.0	30	39	0.03	15	80
SDV1005E140C101 DTSF	14.0	10.0	16.0-22.0	30	39	0.05	20	100
SDV1005E180C150 DTSF	18.0	12.7	22.0-28.0	40	48	0.005	2	15
SDV1005E180C180 DTSF	18.0	12.7	22.0-28.0	40	48	0.01	5	18
SDV1005E180C300□PTSF	18.0	12.7	22.0-28.0	40	48	0.02	10	30
SDV1005E180C500□PTSF	18.0	12.7	22.0-28.0	40	48	0.02	10	50
SDV1005E180C800□PTSF	18.0	12.7	22.0-28.0	40	48	0.03	15	80
SDV1005E260C180□PTSF	26.0	18.4	31.0-38.0	58	70	0.02	5	18
SDV1005E260C300□PTSF	26.0	18.4	31.0-38.0	58	70	0.03	10	30
SDV1005E260C500 DTSF	26.0	18.4	31.0-38.0	58	70	0.03	10	50

III . SDV1005H Series

Part Number	Max. Working Voltage		Varistor Voltage	Max. Clamping Voltage		Rated Single Pulse Transient		Typical Capacitance
Test Condition	<2 DC	0μA AC RMS	@1mA DC	8/20µs	ESD	Energy 10/1000µs	Peak Current 8/20µs	@0.5V _{ms} , 1MHz
Units	Volts	Volts	Volts	Volts	Volts	Joules	Amps	pF
Symbol	V_{WDC}	V_{WAC}	V _B	V _C *1	Vc*2	Eτ	I _P	С
SDV1005H140C100 DTSF	14.0	10.0	16.0-22.0	30	39	0.005	2	10
SDV1005H140C120 DTSF	14.0	10.0	16.0-22.0	30	39	0.005	2	12
SDV1005H180C050 DTSF	18.0	12.7	22.0-28.0	40	48	0.005	2	5
SDV1005H180C100 DTSF	18.0	12.7	22.0-28.0	40	48	0.005	2	10
SDV1005H260C030 DTSF	26.0	18.4	31.0-38.0	58	70	0.003	1	3
SDV1005H260C100 DTSF	26.0	18.4	31.0-38.0	58	70	0.005	2	10

**1: Vc, Maximum peak voltage across the varistor measured at a specified pulse current and waveform.

 Energy Rating
 Pulse & Waveform

 0.00-0.05 Joule
 1A, 8/20µs

 0.10 Joule
 2A, 8/20µs

 0.20-0.50 Joule
 5A, 8/20µs

**2: Vc, Maximum peak voltage across the varistor measured at 30ns after initiation of pulse on IEC61000-4-2 30A/8KV.

%□: Please specify the capacitance tolerance code (N=±30%, Y=+100%~-50%, G=Maximum).

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